

EDIT HISTORY

Version A: Oct.28, 2014

Preliminary Spec.

Version B: Sep. 25, 2015

Add package dimensions.

Manufacture	Examination	Approving
		1



FEATURES

- 0.53 inch (13.60 mm) Digit Height.
- Low current operation.
- Case mold type.
- Gray face, White segment.
- RoHS compliant, Pb Free.

DESCRIPTION

The OPD-AD5330LE-3.5-GW & OPD-AD5331LE-3.5-GW is a 0.53 inch (13.60 mm) height alphanumeric display.

This device utilizes Super Bright Red LED chip which are made from AlGalnP on a transparent GaAs, substrate. The display has Gray face, White segment.

DEVICE

PART NO Super Bright Red	DESCRIPTION
OPD-AD5330LE-3.5-GW	Common Anode
OPD-AD5331LE-3.5-GW	Common Cathode

RoHS Compliance



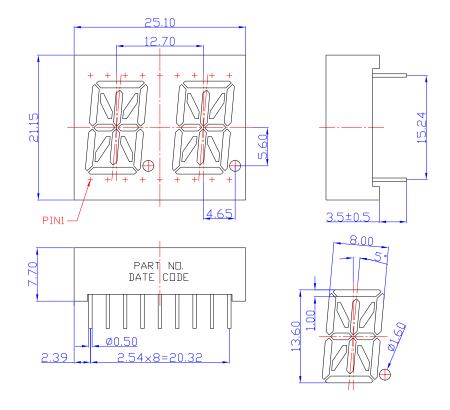
Pb free.



2

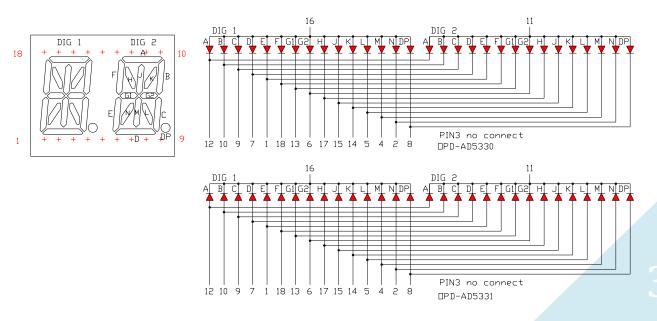


MECHANICAL DIMENSIONS



NOTES: All dimensions are in millimeters. Tolerances are ± 0.25 mm unless otherwise noted.

TYPICAL INTERNAL EQUIVALENT CIRCUIT





● LE: SUPER BRIGHT RED (AlGaInP/GaAs)

ABSOLUTE MAXIMUM RATING AT Ta=25°C

Parameter	Symbol	Super Bright Red	Unit
Power dissipation per dice	P _{AD}	70	mW
Derating liner from 25°C per dice	-	0.33	mA / °C
Continuous forward current per dice	I _{AF}	25	mA
Peak current per dice (duty cycle 1/10, 1kHz)	I _{PF}	90	mA
Reverse voltage per dice	V_{R}	5	V
Operating temperature	T _{OPR}	-25 to +85	°C
Storage temperature	T _{STG}	-25 to +85	°C

ELECTRICAL - OPTICAL CHARACTERISTICS AT Ta=25°C

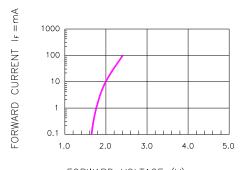
Characteristic	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward voltage	V _F	I _F =20mA	1	2.0	2.6	٧
Reverse current	I _R	V _R =5V	-	-	10	μΑ
Peak wavelength	λР	I _F =20mA	-	632	-	nm
Dominant wavelength	λ _D	I _F =20mA	619	624	629	nm
Luminous intensity	Iv	I _F =20mA	-	60	-	mcd
Spectral radiation bandwidth	Δλ	I _F =20mA	-	20	-	nm

4

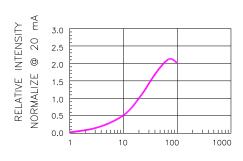


■ LE: SUPER BRIGHT RED (AlGaInP/GaAs) CURVE

Typical Electro-optical Characteristic Curves (25 °C Free Air Temperature Unless Otherwise Specified)



FORWARD VOLTAGE (V)
Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE



FORWARD CURRENT (mA)
Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

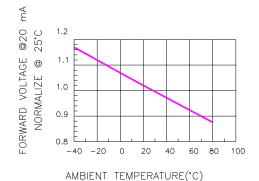


Fig. 3 FORWARD VOLTAGE VS. TEMPERATURE

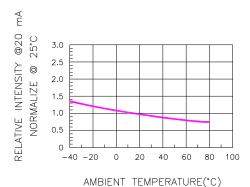


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

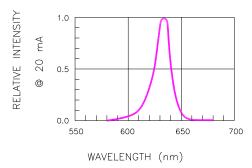


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH

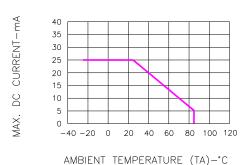
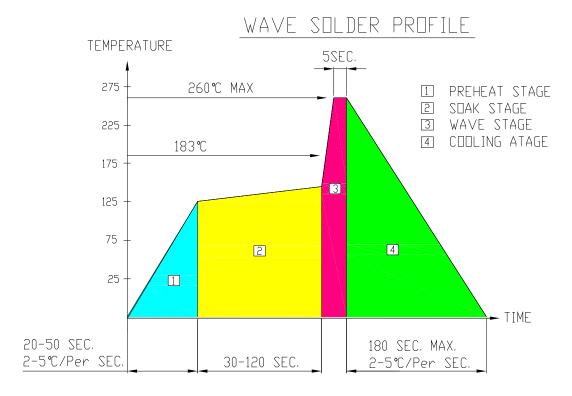


Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE

5



RECOMMEND SOLDERING PROFILE



Note:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 225°C for 3 sec (5 sec max)
- No more than one wave soldering pass

SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within ≦3 sec under 350°C. The head of soldering iron cannot touch copper foil.

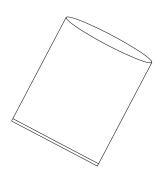


PACKAGE DIMENSIONS

168 PCS(14X12) / 1 Polyform

医眼腺素质 医眼腺素 医眼腺素 医眼腺素 医眼 腺 医	

5 Polyform / 1BAG 840 PCS /1Inner Carton



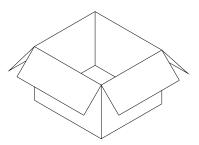
BAG SIZE:450X410X560



INNER BOX SIZE : 394 x 370 x 138 mm

1680 PCS / 2 Inner Carton / 1 Outer Carton





OUTER BOX SIZE : 430 x 390 x 300 mm

Note:

LED DISPLAY STANDARD STORAGED CONDITION

Product in the original packaging material state is the recommended storage conditions.

TERATURE CONDITION	HUMIDITY CONDITION
5°C ~ 30°C	Below 60%RH

If the storage conditions do not meet specification standards, the component pins may become oxidized requiring re-plating and re-sorting before use. Suggest customers consume LEDs as soon as possible, and avoid long-term storage of large inventories.